



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.15mm |
| W | 0.8mm +/-0.15mm |
| T | 0.8mm +/-0.10mm |
| S | 0.7mm MIN |
| B | 0.35mm +/-0.15mm |

Packaging Specifications

| | |
|--------------------|------------------------|
| Packaging | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000 |

General Information

| | |
|------------------|---------------------------------------|
| Series | SMD Comm Y5V |
| Style | SMD Chip |
| Description | SMD, MLCC, General Purpose, Class III |
| Features | Class III |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 6.5 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---|
| Capacitance | 0.47 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 20% |
| Voltage DC | 16 VDC |
| Dielectric Withstanding Voltage | 40 VDC |
| Temperature Range | -30/+85°C |
| Temperature Coefficient | Y5V |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | +22%/-82%, 1kHz 1.0Vrms |
| Dissipation Factor | 7% 1 kHz 1.0Vrms |
| Aging Rate | 7% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 212.8 MOhms |